

Thapar Technology Campus, Bhadson Road
Patiala-147004, Punjab India
Phone: +91 8750777036
Email: npsingh@thapar.edu; harjee.banga@thapar.edu
URL: Thapar.edu

Enquiry No. TIET/CS/HB/22-23/220925

Date : March 2, 2023

Sub: Request for Quotation(s) for the **3D PCB Printing Machine**

Dear Sir

We shall be grateful if you kindly let us have your lowest **quotations** for the following materials. THE QUOTATIONS SHOULD REACH THE UNDERSIGNED **LATEST BY March 10, 2023 @ 11:00 Am** through **courier or e-mail** accompanied by appropriate illustrative literature/catalogues/pamphlets/technical details, samples and specifications as the case may be. **On the quotation envelope/ subject the Enquiry Number & Date should be mentioned on the top of the Envelope/mail subject.**

Sr. No.	Item Name	Qty.
1.0	3d PCB Printing Machine (Technical Specifications As per Annexure I) With consumables Conductivity Ink Cartridge - 2, Solder Paste - 2 & Drill Bits (Various Size) - 10	1 No

The offer sent by you must furnish the following details:

1. Name, Make & specifications of each item.
2. **Price Breakup itemwise with MRP. (Treat it mandatory)**
3. Educational discount if any.
4. **Validity of quotation should be at least 60 Days.**
5. **GST %**
6. **Delivery FOR Central Stores TIET, Patiala**
7. Insurance, Freight & other charges if any.
8. Minimum Delivery Period.
9. **Payment terms. Net 30 days against delivery & satisfactory installation at Thapar Institute, Patiala against submission of PBG of 10% value as per TIET format for defect liability period.**
10. Guarantee / Warranty Information.
11. **Also please share your Companies Turnover and Market Share along with the offer.**

Regards,

Head Commercial

Technical Specifications of 3D PCB printing machine

Printing

Minimum trace width	0.2mm (8mil)*
Minimum package size	1005
Minimum pin-to-pin pitch	0.65mm (32mil)

* Optional Nozzle to reach 0.1mm trace width

Resistivity

	12mΩ/Sq @ 70μm height
Supplied substrate material	FR4
Maximum board thickness	3mm

Soldering

Minimum pin-to-pin pitch	0.5mm (20mil)
Minimum package size	1005
Solder paste alloy	Sn42/Bi57.6/Ag0.4
Solder wire alloy	SnBiAg1
Soldering Iron temperature	180-210°C

Material Compatibility

	Sn42/Bi57.6/Ag0.4 Solder
Standard ink	√
Flexible ink	√
Copper PCBs	√
HASL PCBs	√(brittle)

Drilling

Spindle Speed (maximum)	13,000 RPM
Power	12V, 25W
Runout (TIR)	0.076mm
Shank diameter	3.175mm
Supplied substrate material	FR1
Bit diameter (maximum)	2mm
Bit length (maximum)	38.1mm

Footprint and print BED

Dimensions (L × W × H)	390mm × 257mm × 207mm
Weight	~7kg
Print area	128mm × 105mm
Max. heated bed temperature	240°C

Software requirements

Operating System	Windows 7, 8, 10 (64bit), OSX 10.11+
Compatible file format	Gerber
Connection type	Wired USB 2.0

[Signature]
15/11/2023